UNRF2A3

Silicon NPN epitaxial planar transistor

For digital circuits

■ Features

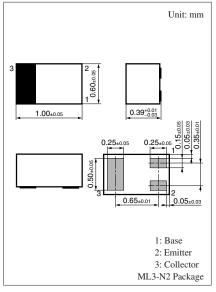
- Reduction of assembly cost and package size with 1006 type mold leadless package is possible
- Maximum package height (0.4 mm) contributes to develop thinner equipments

■ Basic Part Number of Element

• UNR12A3

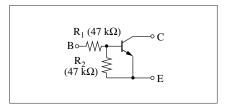
■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter		Symbol	Rating	Unit	
Rating	Collector to base voltage	V_{CBO}	50	V	
of	Collector to emitter voltage	V _{CEO}	50	V	
element	Collector current	I_C	80	mA	
Overall	Total power dissipation	P_{T}	100	mW	
	Junction temperature	T _j	125	°C	
	Storage temperature	T_{stg}	-55 to +125	°C	



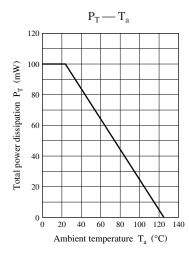
Marking Symbol: 1W

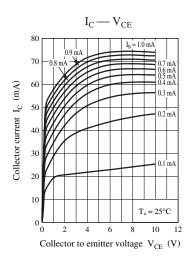
Internal Connection

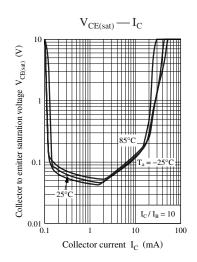


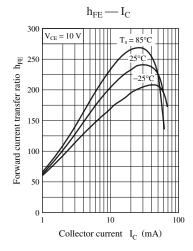
■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

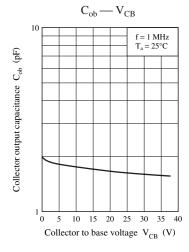
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector to base voltage	V _{CBO}	$I_C = 10 \ \mu A, I_E = 0$	50			V
Collector to emitter voltage	V _{CEO}	$I_C = 2 \text{ mA}, I_B = 0$	50			V
Collector cutoff current	I_{CBO}	$V_{CB} = 50 \text{ V}, I_{E} = 0$			0.1	μΑ
	I _{CEO}	$V_{CE} = 50 \text{ V}, I_{B} = 0$			0.5	
Emitter cutoff current	I_{EBO}	$V_{EB} = 6 \text{ V}, I_{C} = 0$			0.1	mA
Forward current transfer ratio	h _{FE}	$V_{CE} = 10 \text{ V}, I_{C} = 5 \text{ mA}$	80			_
Collector to emitter saturation voltage	V _{CE(sat)}	$I_C = 10 \text{ mA}, I_B = 0.3 \text{ mA}$			0.25	V
High level output voltage	V _{OH}	$V_{CC} = 5 \text{ V}, V_B = 0.5 \text{ V}, R_L = 1 \text{ k}\Omega$	4.9			V
Low level output voltage	V _{OL}	$V_{CC} = 5 \text{ V}, V_B = 3.5 \text{ V}, R_L = 1 \text{ k}\Omega$			0.2	V
Input resistance	R ₁		-30%	47	+30%	kΩ
Resistance ratio	R ₁ / R ₂		0.8	1.0	1.2	_
Gain bandwidth product	f_{T}	$V_{CB} = 10 \text{ V}, I_E = -2 \text{ mA}, f = 200 \text{ MHz}$		150		MHz

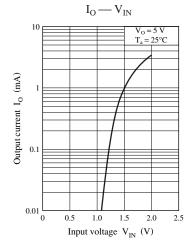


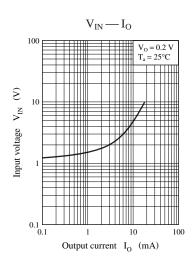












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